

**AMENDMENTS TO THE CLAIMS**

**Listing of claims:**

This listing of claims replaces all prior versions and listings of claims in the application.

Claim 1 (Currently Amended): A test apparatus used for testing a multilayer wiring board being fabricated by stacking wiring layers successively, said test apparatus comprising:

a probe that detects defects in the multilayer wiring board under fabrication ; and

an element supplementing unit that mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe, wherein

the probe tests the multilayer wiring board under fabrication each time an additional element is newly installed; and

the element supplementing unit mounts a new additional element on the multilayer wiring board under fabrication when the probe does not detect defects.

Claim 2 (Previously Presented): The test apparatus as claimed in claim 1, wherein the additional elements to be mounted are included in the element supplementing unit.

Claim 3 (Previously Presented): The test apparatus as claimed in claim 1, wherein the element supplementing unit includes

a first section arranged to face a first side of the multilayer wiring board under fabrication to mount the additional elements on the first side; and

a second section arranged to face a second side of the multilayer wiring board under fabrication to mount the additional elements on the second side.

Claim 4 (Withdrawn): A method of fabricating a multilayer wiring board, comprising:

a first step of testing the multilayer wiring board under fabrication to detect whether defects exist;

a second step of mounting additional elements on the multilayer wiring board under fabrication when no defect is detected;

a third step of testing the multilayer wiring board including the additionally mounted elements; and

a fourth step of continuing or stopping mounting of further additional elements according to testing results of the third step.

Claim 5 (Withdrawn): The method as claimed in claim 4, wherein a test apparatus is provided to test the multilayer wiring board under fabrication and to mount the additional elements, said test apparatus comprising a probe for testing and an element supplementing unit for mounting the additional elements.

Claim 6 (Withdrawn): The method as claimed in claim 5, wherein the additional elements to be mounted are carried by the element supplementing unit.

Claim 7 (Withdrawn): The method as claimed in claim 4, wherein testing and mounting of the additional elements are performed on opposite two sides of the multilayer wiring board under fabrication.

Claim 8 (Previously Presented): The test apparatus as claimed in claim 1, wherein when a defect is detected by the probe in the multilayer wiring board under fabrication, the element supplementing unit disposes of the multilayer wiring board.

Claim 9 (New) The test apparatus as claimed in claim 1, wherein the element supplementing unit comprises a thermosetting resin, and the thermosetting resin is cured when no defect is detected by the probe.